

## **N-Channel Super Junction Power MOSFET II**

### **General Description**

The series of devices use advanced super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

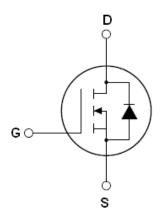
#### **Features**

- New technology for high voltage device
- Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

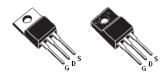
V <sub>DS</sub> @ $T_{jmax}$	650	V
R <sub>DS(ON) MAX</sub>	180	mΩ
$I_D$	21	A



Schematic diagram

### **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE60R180	TO-220	NCE60R180
NCE60R180F	TO-220F	NCE60R180F



TO-220 TO-220F

Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃)

Parameter	Symbol	NCE60R180	NCE60R180F	Unit
Drain-Source Voltage (Vgs=0V)	V <sub>DS</sub>	600		V
Gate-Source Voltage (VDS=0V)	V <sub>G</sub> s	±30		V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	21	21*	Α
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	13.2	13.2*	Α
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	63	63*	Α
Maximum Power Dissipation(Tc=25℃)	P <sub>D</sub>	200	34	W
Derate above 25°C		1.6	0.27	w/°C
Single pulse avalanche energy (Note 2)	Eas	690		mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	7		Α
Repetitive Avalanche energy , $t_{\text{AR}}$ limited by $T_{\text{jmax}}$ (Note 1)	E <sub>AR</sub>	1		mJ



## NCE60R180,NCE60R180F

Parameter	Symbol	NCE60R180	NCE60R180F	Unit
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	≤480 V, dv/dt 50		V/ns	
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V}, I_{SD} < I_D$	dv/dt	15		V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55.	+150	°C

<sup>\*</sup> limited by maximum junction temperature

### **Table 2. Thermal Characteristic**

Parameter	Symbol	NCE60R180	NCE60R180F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	0.62	3.67	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62.5	80	°C /W

Table 3. Electrical Characteristics (TA=25<sup>o</sup>C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	600			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V		0.05	1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V			100	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	2.5	3	3.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10.5A		150	180	mΩ
Dynamic Characteristics						
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> = 20V, I <sub>D</sub> = 10.5A		17.5		S
Input Capacitance	C <sub>lss</sub>	\/ -50\/\/ -0\/		1950		PF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1.0MHz		150		PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVID2		5		PF
Total Gate Charge	Qg	\/ -400\/   -244		45	70	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =480V,I <sub>D</sub> =21A, V <sub>GS</sub> =10V		9		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		18		nC
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		1		Ω
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			11		nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =380V,I <sub>D</sub> =11A,		6		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=4\Omega, V_{GS}=10V$		61	100	nS
Turn-Off Fall Time	t <sub>f</sub>			4.5	12	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T -25°C			21	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			63	Α
Forward on voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =21A,V <sub>GS</sub> =0V		0.9	1.3	V
Reverse Recovery Time	t <sub>rr</sub>	Tj=25°C,I <sub>F</sub> =21A,di/dt=100A/μs		310		nS
Reverse Recovery Charge	Q <sub>rr</sub>			5		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>			28		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

<sup>2.</sup> Tj=25°C,VDD=50V,VG=10V,  $R_G$ =25 $\Omega$ 



### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area for TO-220

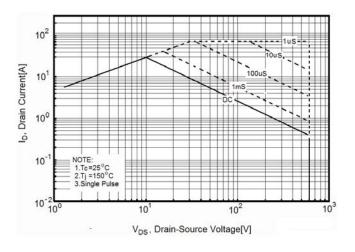


Figure3. Source-Drain Diode Forward Voltage

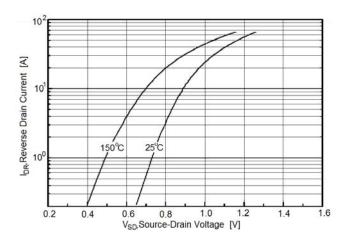


Figure 5. Transfer characteristics

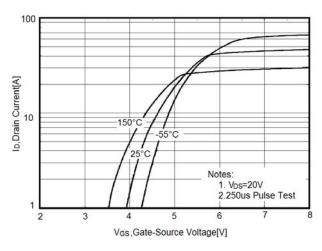


Figure 2. Safe operating area for TO-220F

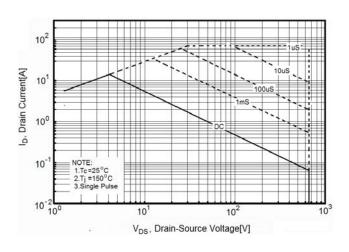


Figure 4. Output characteristics

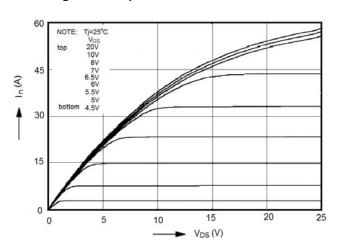


Figure 6. Static drain-source on resistance

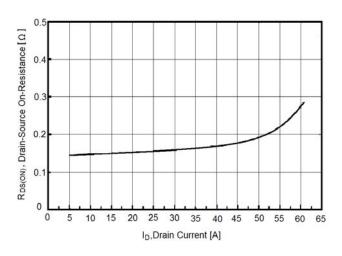






Figure 7. R<sub>DS(ON)</sub> vs Junction Temperature

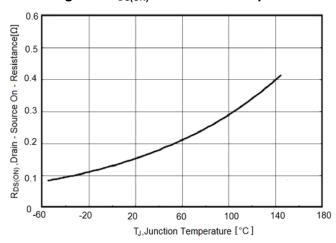


Figure 8. BV<sub>DSS</sub> vs Junction Temperature

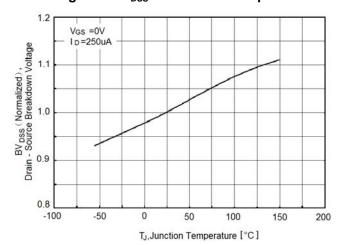


Figure 9. Maximum I<sub>D</sub> vs Junction Temperature

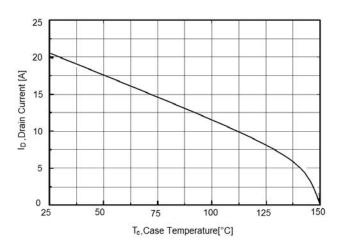


Figure 10. Gate charge waveforms

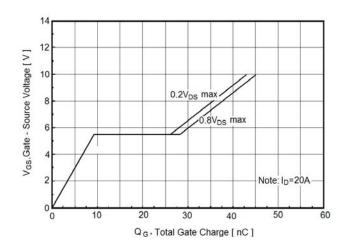


Figure11. Capacitance

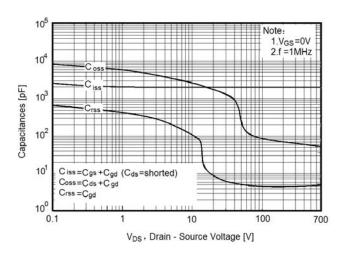


Figure 12. Transient Thermal Impedance for TO-220

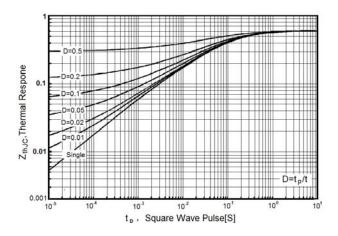
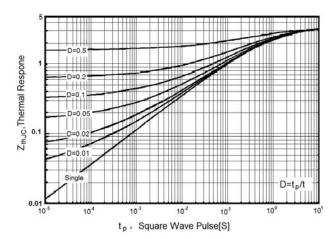




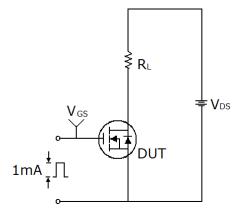
Figure 13. Transient Thermal Impedance for TO-220F

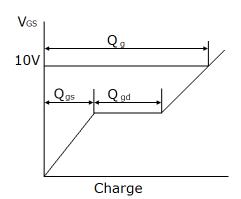




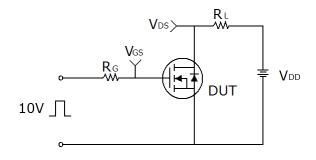
### **Test circuit**

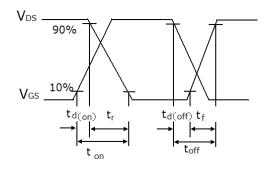
### 1) Gate charge test circuit & Waveform



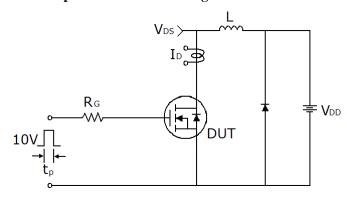


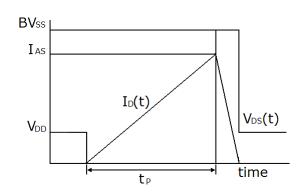
### 2) Switch Time Test Circuit:





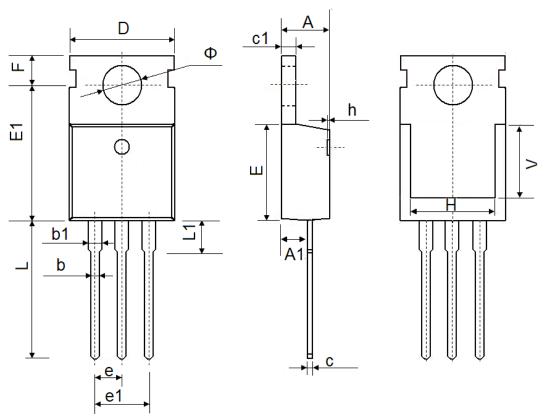
### 3) Unclamped Inductive Switching Test Circuit & Waveforms







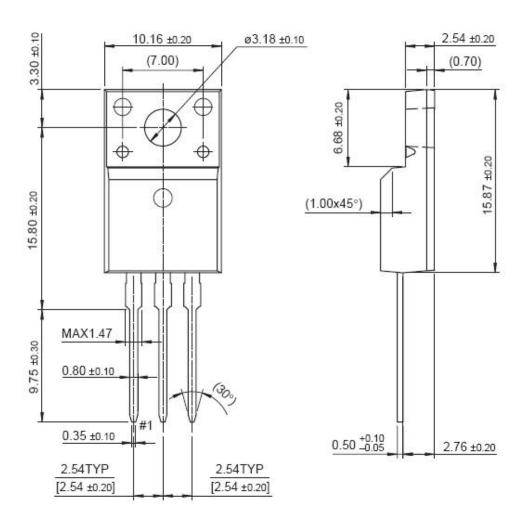
# **TO-220-3L-C Package Information**

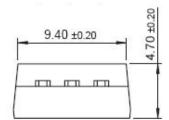


Symbol	Dimensions I	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
Е	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540	TYP.	0.100	TYP.	
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.500	7.500 REF.		REF.	
Ф	3.400	3.800	0.134	0.150	



# **TO-220F Package Information**





Dimensions in Millimeters

## NCE60R180,NCE60R180F



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